

September news and information



Welcome back IMAPS-UK Members, Friends & Supporters to our September newsletter

Food News (or should that be News feed ?)

.... IMAPS-UK is pleased to announce that the "RELPACK" Conference (Reliability Engineering for Electronic Packaging) being organised at STFC Daresbury Labs on 30th November, see below, will now be preceded by an informal get together for an evening meal at the "Ring O'Bells" restaurant in Daresbury on the evening of Wednesday 29 November. Tickets for this can be booked on-line at the event registration area on the website www.imaps.org.uk.

(note - bookings for the dinner will close on November 15)

EVENT News ...

THE Packaging Workshop -

28 September - sponsored by





and hosted by

As you may know, "The Packaging Workshop" is well oversubscribed and although we have a waiting list it is probably better to repeat this event at the end of this year or early next year as

..... THE NEXT PACKAGING WORKSHOP

Those who have put their names down on the waiting list will get priority booking for this repeat event. Do let us know if you wish to be part of the next event .. there will be opportunities for sponsoring, hosting and presenting. Please send me an e-mail message to indicate your interest.

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Reliability Engineering for Electronic Packaging

The "RELPACK" Conference

.... is on 30 November at STFC Daresbury Labs.

This event is a conference with a table top exhibition..
Book early to avoid disappointment, as places are limited for both exhibitors and delegates.

The Conference programme and full details are on the website - book your place early to avoid missing out.

[Click HERE for more information on this event.](#)

Places are already being booked so consider booking your place now and remember to book the dinner as well

OUR BIG EVENT FOR 2018 is MICROTECH

it's our 50th Anniversary ... 1968 - 2018

Please help us celebrate in style - be part of the fun !



IS PACKAGING MORE THAN MOORE ?

We think so and after 50 Years since ISHM was founded and later became iMAPS ... much has changed and much "moore" will change in the future ...

The 2018 Microtech conference, the annual conference of iMAPS-UK marks 50 years for the International Microelectronics Assembly and Packaging Society in UK – and we are celebrating! On 9 April, the evening before MicroTech, we will have a Gala Dinner event at the same site as the conference - the Royal Holloway College in Egham Surrey, near London. Do book to join us at this special event. The Conference and the AGM on 10 April will be held on site that the RHC Windsor Conference Centre.

The Gala Dinner will feature Company and Individual of the Year Awards, plus a keynote providing an insight into the future Technologies and Trends and a special presentation looking at the development of iMAPS-UK and the various microelectronics packaging technologies we see today.

MOORE THAN PACKAGING: 50 Years Gone; 50 Years On!

The Society's 50th Annual Conference on the 10th April, is also at the prestigious Royal Holloway Windsor Conference Centre in Egham Surrey.

Continuing the events theme “MOORE THAN PACKAGING: 50 Years Gone; 50 Years on”, the Conference will bring together experts from across the microelectronics sector to discuss the latest technologies and developments, as well as providing a platform to highlight current commercial opportunities.

Sessions will cover: Process & Technologies, Materials, Applications and Trends, followed by a Panel Session looking at the future direction, challenges and technologies our industry faces.

BOOK THE DATES NOW - Workshops followed by a Gala Dinner on 9 April and the Conference/AGM on 10 April.

There are opportunities for Exhibitors, Sponsors and Speakers

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EVENTS WE ARE PLANNING FOR 2018

January 2018 - A repeat of the Packaging Workshop

February 2018 - An Advanced Packaging Workshop

June 2018 - Workshop/Symposium about Substrates

Week of 22-26 October 2018 "Optronics"

- A conference and Table top exhibition at South Devon College, Torbay - supported by the Torbay High Tech Forum.

December 2018 - Packaging for Space Applications

SOME OTHER EVENTS >>>>>

[PEUK: Thermal Management Workshop](#)

3M, Bracknell - Sept 21

Market requirements for power electronics and RF power devices are driver higher power densities and the need to operate in higher temperature environments. As a result, thermal management of



devices and systems is a key design and manufacturing challenge.

The aim of this workshop is to bring together the power electronics and power RF communities to discuss trends and directions in device and systems thermal management to encourage best practice and the development of new supply chain collaborations in R&D.

Topics within scope include:

- The integration of new high performance materials into systems for thermal management and harsh environment performance.
- Active cooling and thermal management designs and configuration in power electronics and power RF systems
- Passive cooling mechanisms and designs.
- Thermal modelling and characterisation
- [Register here](#)



Centre for Power Electronics - Wide Band-Gap Event 2017

Realising the True Potential of Wide Band-Gap Power Electronics

Wednesday 11 October 2017

Jubilee Conference Centre

University of Nottingham

This **free** event will explore the future direction of Wide Band-Gap Power Electronics. It will be of interest to those working in the field, whether you are from academia or from industry.

The agenda will include:

- Highlights of previous Centre for Power Electronics research in this field .
- An introduction to our work in this area for the next three years.
- Updates on the latest developments from Power Electronics UK, the Compound Semiconductor Applications Catapult and leading semiconductor manufacturers.
- The Future Power Challenge, a competition to stimulate university / industry research.
- An overview of the relevant strategic initiatives relating to Wide Band-Gap Power Electronics
- An opportunity to take part in cross-sector workshops to provide input into the industrial strategy for UK Power Electronics.

[Register your interest](#)

Places are limited and in the event of oversubscription representation from individual organisations will be limited accordingly.

The deadline for registration is **8 September 2017**

We will confirm your place by email by **12 September 2017**

The Power Electronics Expo UK

This event runs 15th March 2018 at the International Centre, Telford in the West Midlands, a major hub of the UK's high tech industrial sector. See www.powerelectronicsexpo.co.uk

Power Electronics is driving significant change across a range of industry sectors including the renewable energy generation, energy networks, transportation and industrial processes arenas. The event will provide a unique opportunity for businesses in the field to showcase their latest products, technologies and services. Should you wish to reserve space to exhibit, the organisers are offering a 15% discount on the price of a single space until the end of July.

**SEMICON[®]
EUROPA**

Advanced Packaging Conference:

"Electronics Packaging and Test for Future Mobility"

The registration for the SEMICON Europa 2017 is now open. This event is on at the same time as Productronica in Munich. It will also include the Advanced Packaging Conference ... which this year is about "Electronics Packaging and Test for Future Mobility"see [here](#) for the full details:

SEMI have offered a 10% discount for IMAPS-UK members who wish to attend this conference. Please contact me at the secretariat for the discount code to use when booking your place.

As a further bonus, all registered conference attendees will receive in their confirmation a promo code to get free access to the Productronica show floor – separate registration is mandatory.

SMART NEWS:

SMTA and SMART Group announce plans for SMART Group to become SMTA Europe effective January 1, 2018. SMTA Europe will continue to host meetings in the UK, but will also support manufacturing regions in mainland Europe with additional educational programs and technical resources. Members of both organizations will benefit with expanded opportunities to connect across the globe as well as mutual access to thousands of technical papers and online content.

This announcement comes months after the successful **Contamination, Cleaning and Coating Conference co-organized by SMTA and SMART Group in Amsterdam**. Plans are already underway for a 2018 conference in Amsterdam addressing Electronics in Harsh Environments. "In this fast changing environment, industry associations can struggle to remain relevant and this will ensure that our growth continues," said Keith Bryant, Chairman of SMART Group. "SMTA is a global organization with a huge reach. Together we will offer our members unrivalled events and support, increasing their knowledge, helping those overcome problems and become more successful."

"The SMART Group mission and values perfectly align with that of SMTA," said Tanya Martin, Executive Director for SMTA. "The SMART Group has built a solid foundation and we look forward to welcoming their members into our family. This is an exciting time for SMTA as we strive to expand our international presence and bring education and connections to electronics professionals around the world."

SMTA - A Global Association Working at a Local Level

Established in 1984, the SMTA membership is an international network of professionals who build skills, share practical experience and develop solutions in electronic assembly technologies, including microsystems, emerging technologies, and related business operations.

NEWS FROM THE WIRES:

The Global Hermetic Packaging Market is poised to grow at a CAGR of around 6.5% over the next decade to reach approximately \$5.21 billion by 2025. The report is from Research and Markets.

Based on type, the market is categorized into passivation glass, reed glass, ceramic-metal sealing (CERTM), transponder glass and glass-metal sealing (GTMS).

Depending on the package closing technique the market is segmented by soldering, welding and crimp connection. Welding is further sub segmented into laser welding, cold welding electrical resistance welding and rolled seam welding.

By configuration, market is segregated by pressed ceramic packages, multilayer ceramic packages and metal can packages.

Based on end user the market is categorized into energy and nuclear safety, telecommunication, aeronautics and space, medical, military and defense,

SiTEST has a small cleanroom facility, with which they offer pre-production runs, sub-contract work, repair or simply just machine demonstrations. Annual maintenance, service contracts, emergency support, remote diagnostics are all standard services expected in the industry, they aim to meet them all. They currently have a G5 wirebonder available for both demonstration and prototyping installed at The Manufacturing Technology Centre (MTC) in Coventry. and urge the members to take advantage of this installation. See www.sitest.co.uk

Membership of iMAPS-UK

Not a Member ? Join NOW and enjoy more Any new members joining from now onwards will be enrolled as members for the rest of 2017 and all of 2018

Remember IMAPS-UK membership key benefits are:

- Member to member exchange
- Expand your contacts
- Regular newsletters and bulletins
- Discounted registration at IMAPS events globally
- 50 (free) downloads from the "iMAPSource" Knowledge library
- Receive Advancing Microelectronics magazine
- Free affiliate membership of IMAPS North America
- A vote at the IMAPS-UK AGM

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Thanks for reading this - please let the office know if you want more information or would like to contribute to the October newsletter...

I hope to see you at one of our events soon

Best regards
Andy Longford - IMAPS-UK Secretariat

This e-mail newsletter has been sent to you by
IMAPS-UK Secretariat - Andy Longford - on
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